



## **Rambus to Discuss Challenges for Next-Generation Mobile and Graphics Memory at Intel Developer Forum 2010**

SAN FRANCISCO, Sep 13, 2010 (BUSINESS WIRE) -- Rambus Inc. (NASDAQ: RMBS):

Who: Rambus Inc. (NASDAQ: RMBS)

Where: Intel Developer Forum 2010

Booth #207

Moscone Center West

San Francisco, California

When: September 13-15, 2010

Join Rambus, one of the world's premier technology licensing companies, at the Intel Developer Forum 2010 to learn more about next-generation memory solutions for mobile and graphics applications. In addition, Rambus will exhibit demos of its award-winning innovations including its XDR(TM) memory product showcase.

### **Rambus Presentation**

Monday, September 13, 4:25 p.m. PT

"Meeting the Challenges for Next-Generation Mobile and Graphics Memory"

Presented by Dr. Judy Chen, strategic development director and Dr. Steve Woo, technical director at Rambus

Moscone Center West, Room 2011

During the session, Drs. Chen and Woo will discuss how next-generation mobile and graphics systems share the need for higher-performance, power-efficient memory in order to deliver compelling consumer experiences. They will outline techniques to help address the challenges of managing signal and power integrity, reducing component and board costs, and delivering multi-modal functionality.

### **Rambus Demos and Displays**

The product showcase will exhibit high-performance, power-efficient, and innovative designs in some of today's most compelling electronics products. Rambus will demonstrate its latest technology developments in the areas of mobile, gaming and graphics, and computing main memory solutions.

### **Mobile XDR(TM) Memory Architecture**

The fastest and most power-efficient memory for mobile applications. Capable of achieving data rates of 3.2 to 4.3 gigabits per second (Gbps) at an unprecedented power efficiency of 2.2 milliwatts per gigabit per second (mW/Gbps), Mobile XDR memory is ideal for next-generation smartphones, netbooks, mobile gaming and mobile multimedia products.

### **DDR3 PHY Development Package**

This high-performance, low-cost DDR3 memory controller interface solution is tailored for consumer electronics. The solution is the first to demonstrate operation in working silicon at a data rate of 1866 megatransfers per second (MT/s) in a low-cost wire bond package.

### **XDR 2 Memory Architecture**

Designed for scalability, power efficiency and manufacturability, the XDR 2 memory architecture is a complete memory solution ideally suited for high-performance gaming, graphics and multi-core computing applications.

## DDR3 Module Threading Demonstration

Driven by multi-core computing, virtualization and processor integration trends, the industry needs a next-generation main memory solution capable of achieving data rates of up to 3200MT/s in the same, or lower power envelope as the current DDR3 1600MT/s memory solution. This system demo will show how the innovation of Module Threading can be used to boost memory throughput at reduced power.

### About Rambus Inc.

Rambus is one of the world's premier technology licensing companies. Founded in 1990, the Company specializes in the invention and design of architectures focused on enhancing the end-user experience of electronic systems. Rambus' patented innovations and breakthrough technologies help industry-leading companies bring superior products to market. Rambus licenses both its world-class patent portfolio, as well as its family of leadership and industry-standard solutions. Headquartered in Los Altos, California, Rambus has regional offices in North Carolina, Ohio, India, Germany, Japan, and Taiwan. Additional information is available at [www.rambus.com](http://www.rambus.com).

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